



## Advanced High Voltage Passive devices for Automotive and Power applications

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INNOVATOR IN ELECTRONICS







## Outline



- □ Introduction to Murata Integrated Passive Solutions
- □ Which technologies and products are made today?
- □ What are we targeting for the future and especially in IPCEI?
- □ Focus on high voltage and power applications

Conclusion







## We are part of Murata group





#### **Our Business**

We are worldwide leaders in the design, manufacture and supply of electronic components and solutions. We are Innovators in Electronics.

#### **Our Strengths**

- Advanced materials technology and expertise
- Broad product portfolio
- Extensive global manufacturing and sales network

#### **Our Figures**

- Net sales 1,534,045 million JPY (2019)
- Employees 74,109 as of March 2020
- Number of subsidiaries 92 (28 in Japan, 64 overseas)
- Established in 1944

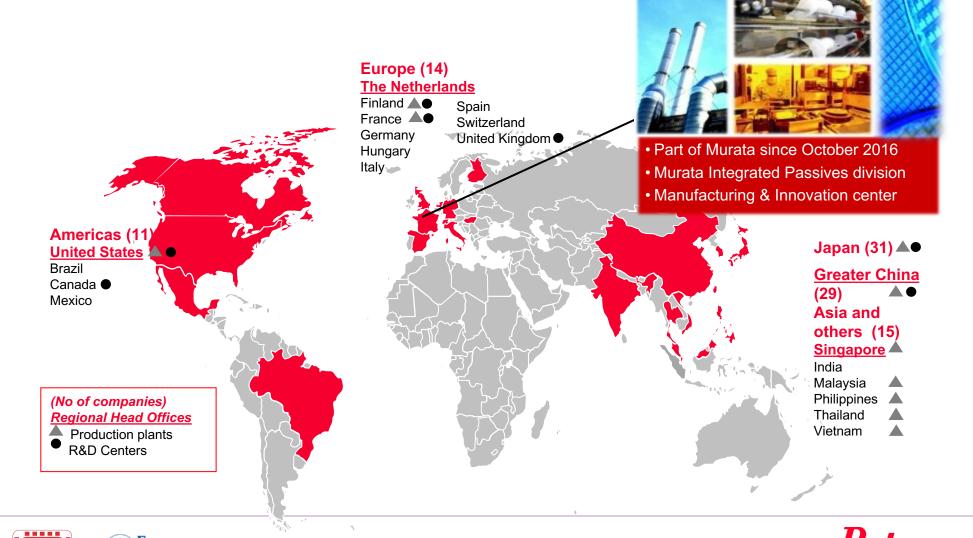








## Murata Integrated Passive Solutions









## Our technology



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#### **3D Silicon Capacitors**

#### 3D:

We have invented a unique technology based on **3D structures**.

These structures enable high level of **integration** and **miniaturization** of capacitors.

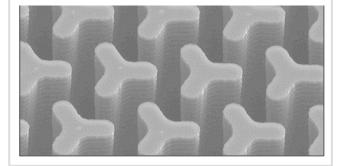
#### Silicon:

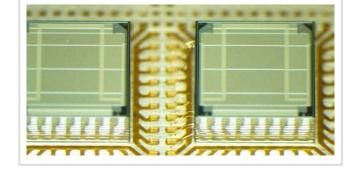
Our technology is based upon **silicon** components. Silicon capacitors can reach **outstanding performances** in stability, frequency and temperature

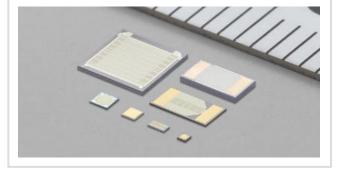


#### **Capacitors:**

We are specialized in integrating **passive components (custom and off-the-shelf)**, with a strong focus on high performances **capacitors**.







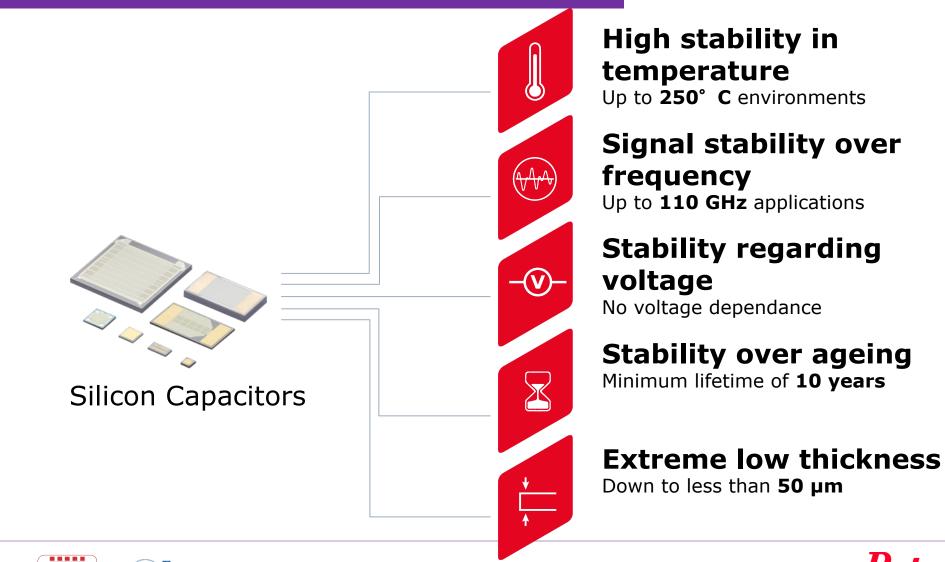






## What does Silicon bring?











## Where are they used today?





□ Widely used in Implantable Devices like pakemakers, stimulators, etc...

- Also adopted in High Speed Data communication modules (optical and wireless) and in High Reliability Industrial applications
- □ Voltage range today is from 6V to 150V

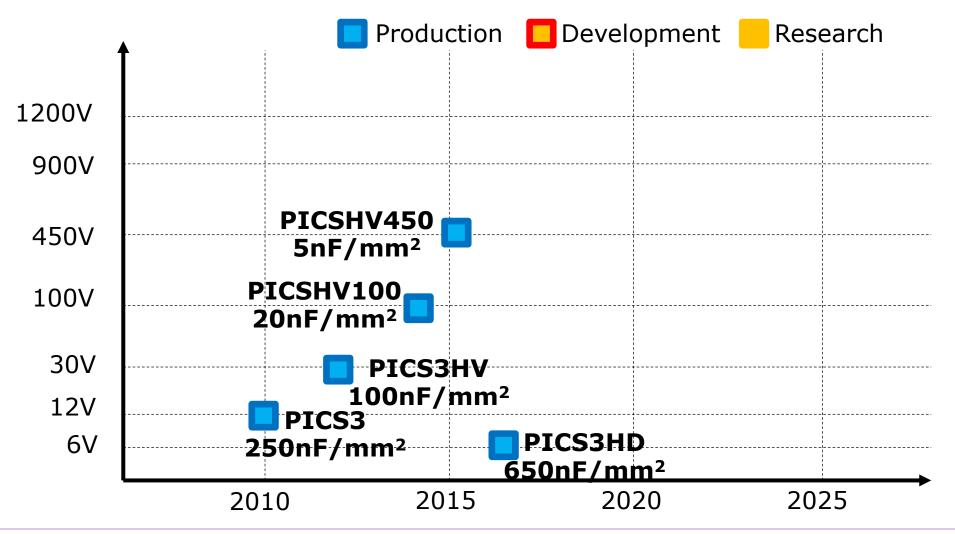






# Which part of the roadmap is developed in IPCEI?





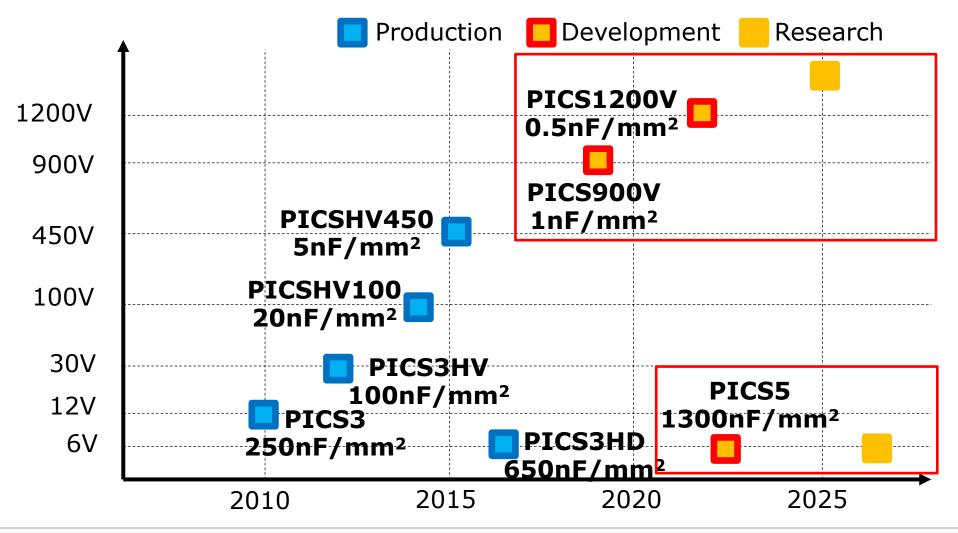






# Which part of the roadmap is developed in IPCEI?



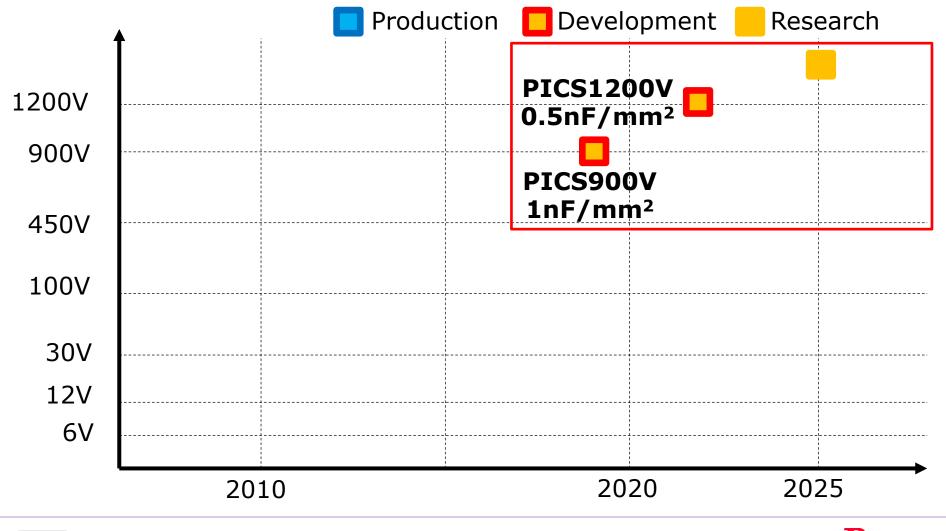










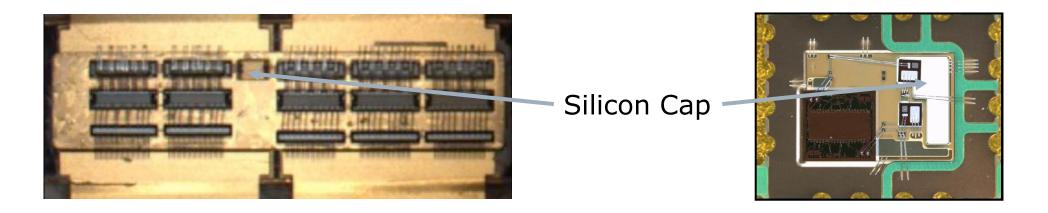












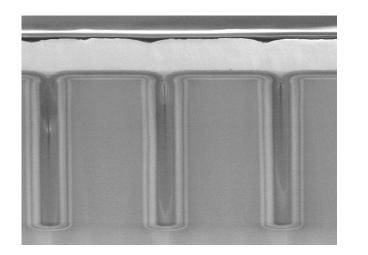
- □ One of the first challenges is Packaging and Thermal management
- This has been studied heavily for products used in RF Power transistors for Base Stations and integrated HV SiPs
- □ These products are using process nodes up to 150V for Si LDMOS or GaN transistors but the component structure is very similar to higher voltages
- We confirmed the possibility to use the same assembly technologies for Capacitors than for power transistors (wirebond mainly)

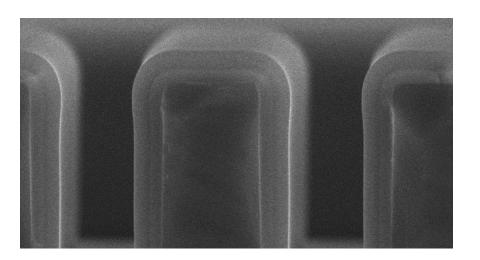












- The second important challenge is the deposition of high voltage dielectric material in high aspect ratio 3D structures
- The current R&D projects are concentrating on Silicon OxyNitride to ensure a high reliability and low leakage
- □ Next generations (>1200V) will require alternative solutions









- Our third challenge is more related to the definition of required characteristics of passive components
- Silicon passive components show some properties that are different from standard passive components
- This is changing the way of working of module design engineers : critical passive components should be designed also at the beginning of the projects, together with active functions









Thanks to this cooperative R&D project, we have been able to associate advanced power module designers with end users (mainly in automotive) and our advanced technology development teams

Conclusions and perspectives

- This is allowing early definition and adoption of new technologies like Silicon passive components for high voltage and power!
- □ Targeted functions are :
  - DC-DC converters
  - On Board Chargers
  - Inverters
    - ...







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